

ABSTRACT OF THE DISCLOSURE

Disclosed herein is a method for forming a solder resist pattern which can replace conventional solder resist printing processes. The method for forming a solder resist pattern comprises the steps of: laminating a semi-cured thermosetting film on both sides of a substrate; and laser ablating the laminated thermosetting film according to a solder resist mask pattern.

The present method for forming a solder resist pattern is applicable to multilayer printed circuit boards which are fabricated by either buildup process or in a parallel manner. According to the present invention, low manufacturing cost and improved accuracy of the pattern can be achieved due to simplified process